



Material Content Data Sheet



Sales Product Name		ICE3BR4765JG		Issued		25. September 2017		
MA#		MA001510676						
Package		PG-DSO-12-19		Weight*		154.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.867	1.21	1.21	12053	12053
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.069	0.04		447	
	non noble metal	iron	7439-89-6	1.386	0.89		8948	
wire	non noble metal	copper	7440-50-8	56.286	36.33	37.27	363323	372830
	noble metal	gold	7440-57-5	0.223	0.14	0.14	1440	1440
	encapsulation	organic material	carbon black	1333-86-4	0.278	0.18		1794
encapsulation	plastics	epoxy resin	-	10.836	6.99		69947	
	inorganic material	silicondioxide	60676-86-0	81.503	52.62	59.79	526100	597841
leadfinish	non noble metal	tin	7440-31-5	1.143	0.74	0.74	7376	7376
plating	noble metal	silver	7440-22-4	0.428	0.28	0.28	2766	2766
glue	plastics	epoxy resin	-	0.132	0.09		854	
	noble metal	silver	7440-22-4	0.750	0.48	0.57	4840	5694
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com